# Coiltronics HCM0703 Series

## High current power inductors



#### **Product description**

- · High current carrying capacity
- · Low core losses
- · Magnetically shielded, low EMI
- · Frequency range up to 5MHz
- · Inductance range from 0.15μH to 33μH
- · Current range from 1.8A to 52A
- 7.4x7.0mm footprint surface mount package in a 3.0mm height
- · Powder iron core material
- · Halogen free, lead free, RoHS compliant

#### **Applications**

- · Voltage Regulator Module (VRM)
- · Multi-phase regulators
- · Point-of-load modules
- · Desktop and server VRMs and EVRDs
- · Base station equipment
- · Notebook regulators
- · Battery power systems
- · Graphics cards
- · Data networking and storage systems

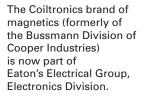
#### **Environmental data**

- Storage temperature range (Component): -55°C to +125°C
- Operating temperature range: -55°C to +125°C (ambient + self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant













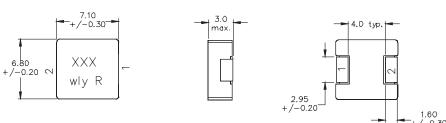


## **Product specifications**

Part Number <sup>6</sup>	OCL¹ (μΗ) ±20%	FLL min.² (µH)	I <sub>rms</sub> ³ (amps)	l <sub>sat</sub> 4 (amps)	DCR (mΩ) @ 20°C Typical	DCR (mΩ) @ 20°C Maximum	K-factor⁵
HCM0703-R15-R	0.15	0.09	26.0	52.0	1.90	2.50	1044
HCM0703-R22-R	0.22	0.13	23.0	40.0	2.50	2.80	986
HCM0703-R47-R	0.47	0.28	17.5	26.0	4.00	4.20	580
HCM0703-R68-R	0.68	0.41	15.5	25.0	5.00	5.50	455
HCM0703-R82-R	0.82	0.49	13.0	24.0	6.70	8.00	439
HCM0703-1R0-R	1.00	0.60	11.0	22.0	9.00	10.0	374
HCM0703-1R5-R	1.50	0.90	9.00	18.0	14.0	15.0	366
HCM0703-2R2-R	2.20	1.32	8.00	14.0	18.0	20.0	281
HCM0703-3R3-R	3.30	1.98	6.00	13.5	28.0	30.0	252
HCM0703-4R7-R	4.70	2.82	5.50	10.0	37.0	40.0	210
HCM0703-6R8-R	6.80	4.08	4.50	8.00	54.0	60.0	151
HCM0703-8R2-R	8.20	4.92	4.00	7.50	64.0	68.0	142
HCM0703-100-R	10.0	6.00	3.20	7.00	70.5	77.6	132
HCM0703-220-R	22.0	14.1	2.30	3.00	135.3	148.8	83
HCM0703-330-R	33.0	19.8	1.80	2.20	220	242	76

- 1. Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.25V<sub>rms</sub>, 0.0Adc,
- 2. Full Load Inductance (FLL) Test Parameters: 100kHz, 0.25V $_{\rm ms}$ , I  $_{\rm sat}$ , @ +25°C.
- 3.1 DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.
- 4. I Peak current for approximately 20% rolloff at +25°C.
- 5. K-factor: Used to determine  $B_{p,p}$  for core loss (see graph).  $B_{p,p} = K * L * \Delta I$ .  $B_{po}$ : (Gauss), K: (K-factor from table), L: (Inductance in  $\mu H$ ),  $\Delta I$  (Peak to peak ripple current in amps).
- 6. Part Number Definition: HCM0703-yyy-R
  - HCM0703 = Product code and size
  - yyy= Inductance value in  $\mu H$ , R = decimal point, if no R is present then third character = number of zeros.
  - "-R" suffix = RoHS compliant

#### **Dimensions - mm**

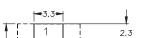


1.60 /-0.30

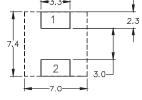
Part marking: xxx= Inductance value in uH, R= decimal point, If no R is present then last

digit is # of zeroes wly= Date code, R= Revision level

All soldering surfaces to be coplanar within 0.10 millimeters Tolerances are ±0.3 millimeters unless stated otherwise. Color: Grey



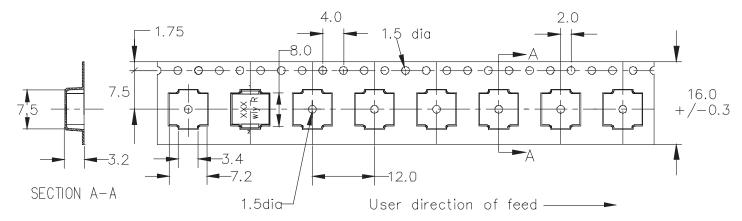
Recommended Pad Layout





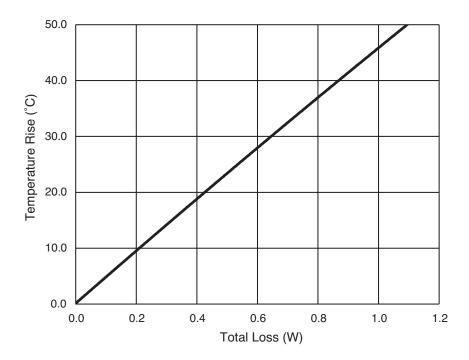
Schematic

## Packaging information - mm

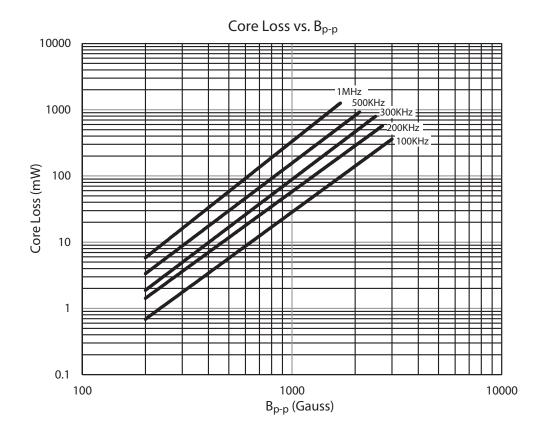


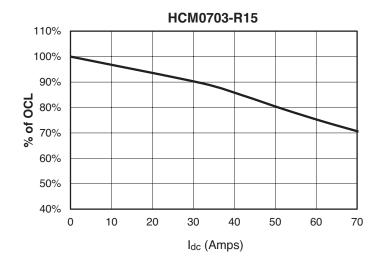
Supplied in tape and reel packaging, 1500 parts per 13" diameter reel.

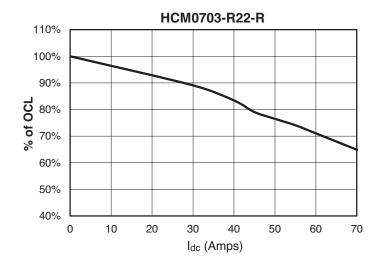
## Temperature rise vs. total loss

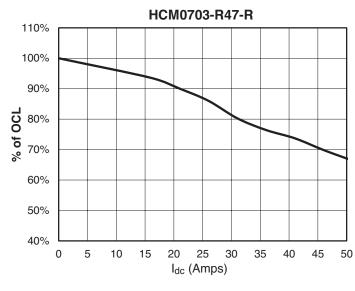


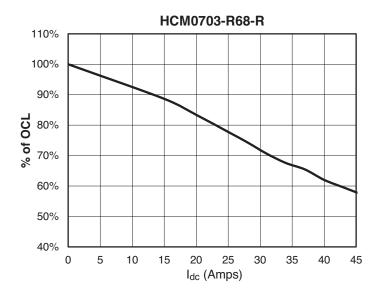
## **Core loss**

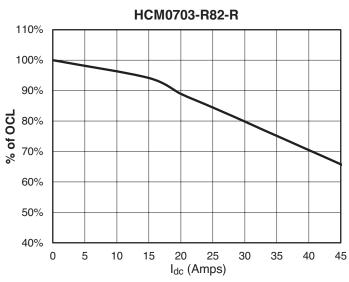


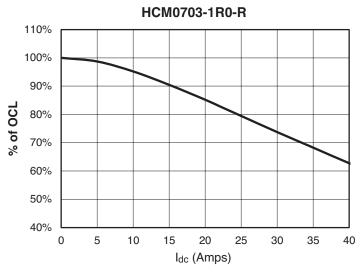


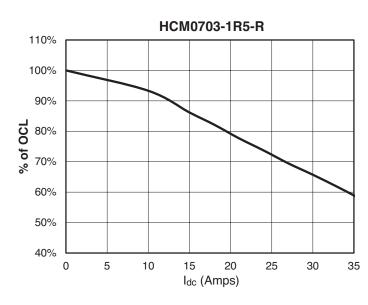


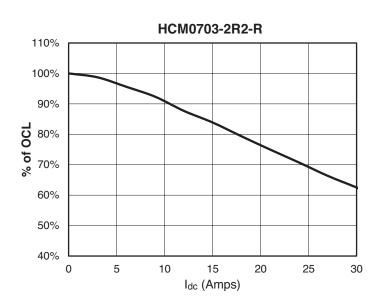


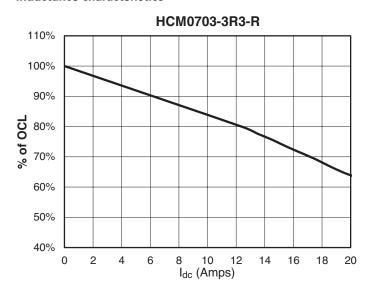


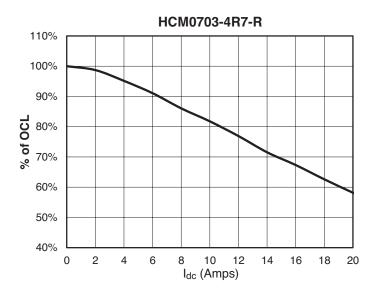


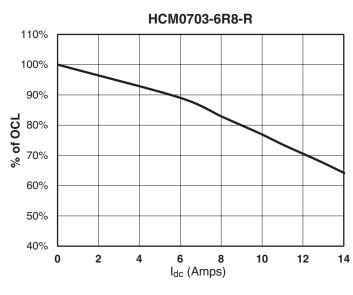


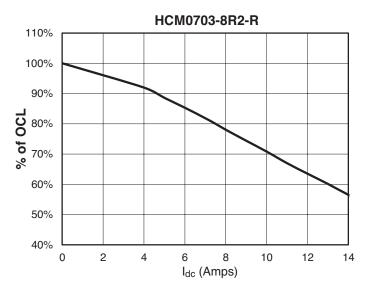


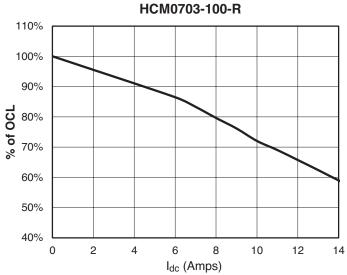


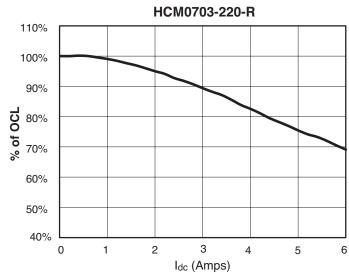


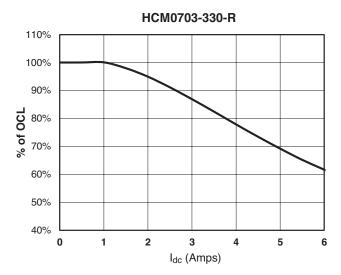












#### Solder reflow profile

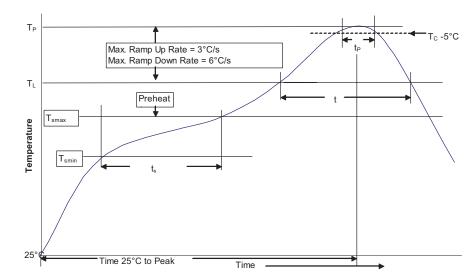


Table 1 - Standard SnPb Solder (T<sub>c</sub>)

	Volume	Volume
Package	mm <sup>3</sup>	mm <sup>3</sup>
Thickness	<350	≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T<sub>C</sub>)

Package	Volume mm <sup>3</sup>	Volume mm³	Volume mm³
Thickness	<350	350 - 2000	>2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

#### **Reference JDEC J-STD-020D**

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. (T <sub>smin</sub> )	100°C	150°C
	Temperature max. (T <sub>smax</sub> )	150°C	200°C
	• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds	60-120 Seconds
Average ramp up rate T <sub>Smax</sub> to T <sub>p</sub>		3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (TL)		183°C	217°C
Time at liquidous (t <sub>L</sub> )		60-150 Seconds	60-150 Seconds
Peak package body temperature (Tp)*		Table 1	Table 2
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature $(T_c)$		20 Seconds**	30 Seconds**
Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> )		6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.

<sup>\*</sup> Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

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<sup>\*\*</sup> Tolerance for time at peak profile temperature  $(t_p)$  is defined as a supplier minimum and a user maximum.